

2022  
DESIGN AND VERIFICATION™  
**DVCON**  
CONFERENCE AND EXHIBITION  
**EUROPE**  
MUNICH, GERMANY  
DECEMBER 6 - 7, 2022

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**2022**  
CONFERENCE  
**PROGRAM**

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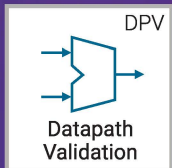
**SYSTEMS INITIATIVE**

## Synopsys VC Formal

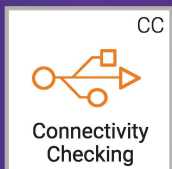
Leading formal innovations with many **firsts in industry**, supporting innovative applications and methods such as:



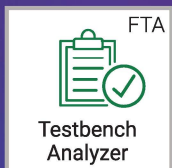
Applying AI/ML to improve formal performance, convergence, and debug



Verifying datapath elements in CPU, GPU, AI/ML, and other compute intensive designs

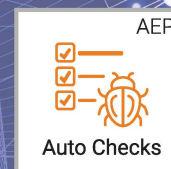
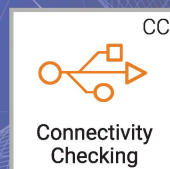
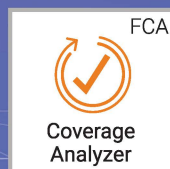
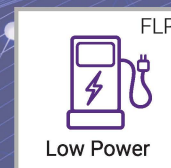
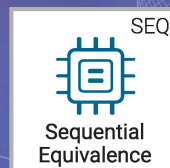
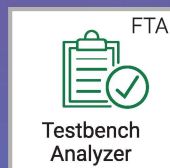
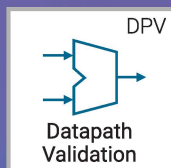


Performing formal connectivity checking at the SoC level



Using mutation technology as a strict metric for formal signoff

## Synopsys VC Formal Best-in-Class Apps



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## DVCon Europe 2022



Welcome Message from DVCon Europe General Chair,  
**Sumit Jha**  
General Chair - Qualcomm Technologies

Dear friends,

Good News!! DVCon Europe is returning to its usual conference venue in Munich for an in-person conference and it is my pleasure to welcome you all to the 9<sup>th</sup> edition of DVCon Europe planned on 6<sup>th</sup> and 7<sup>th</sup> December 2022, along with Accellera's co-located SystemC Evolution Day on 8<sup>th</sup> December 2022.

From covid 19 to chip shortage and now the ongoing geopolitical crisis, it seems like we are living in a dramatic part of the history, where nothing can be taken for granted. In this ever-changing global scenario, one thing which remains constant is the relevance and importance of science and technology, which heavily depends on our semiconductor industry.

The Design and Verification Conference & Exhibition Europe (DVCon Europe) is the premier European technical conference on system, software, design, verification, validation, and integration. It is a place where the latest methodologies and technologies for the industrial use of tools, languages, and standards for integrated and embedded systems and products are shared and discussed.

DVCon Europe, sponsored by Accellera, provides attendees around the globe with the industry's most comprehensive technical program focused on the design and verification of electronic systems. It is also that time of the year when we celebrate, promote and reward some of the brilliant ideas from the authors who are carefully shortlisted from a large number of submissions. We also get an opportunity to hear from industry leaders in form of keynotes and panel sessions.

Last year, DVCon Europe 2021 virtual conference, was a huge success and very well received by the record high number of attendees across the globe.

I look forward to your enthusiastic participation, to reflect upon and celebrate innovation, renew friendship, extend your networks, and jointly explore current and future innovation opportunities. The steering committee is confident that this conference will be yet another stimulating, productive and memorable event. Also, I hope that the vibrant Munich city will add to the pleasure of the conference and create lasting memories.

Looking forward to meeting you in Munich.



**Sumit Jha - DVCon Europe General Chair**



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## CONFERENCE SPONSOR

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### SYSTEMS INITIATIVE

Accellera Systems Initiative is an independent, not-for profit organization dedicated to create, support, promote, and advance system-level design, modeling, and verification standards for use by the worldwide electronics industry. We are composed of a broad range of members that fully support the work of our technical committee to develop technology standards that are balanced, open, and benefit the worldwide electronics industry. Leading companies and semiconductor manufacturers around the world are using our electronic design automation (EDA) and intellectual property (IP) standards in a wide range of projects in numerous application areas to develop consumer, mobile, wireless, automotive, and other "smart" electronic devices. Through an ongoing partnership with the IEEE, standards and technical implementations developed by Accellera Systems Initiative are contributed to the IEEE for formal standardization and ongoing governance.

#### Our Mission

At Accellera our mission is to provide a platform in which the electronics industry can collaborate to innovate and deliver global standards that improve design and verification productivity for electronics products.

#### The purposes of the organization include:

- » Provide design and verification standards required by systems, semiconductor, IP, and design tool companies to enhance a front-end design automation process.
- » Collaborate with our community of companies, individuals, and organizations to deliver standards that lower the cost of designing commercial IC and EDA products and embedded system solutions, as well as increase the productivity of designers worldwide.
- » Encourage availability and adoption of next-generation EDA and IP standards that encompass system-level, RT-level, and gate-level design flows.
- » Collaborate with the electronic design community to deliver standards that increase designer productivity and lower the cost of product development.
- » Provide mechanisms that enable the continued growth of the Accellera Systems Initiative user community including SystemC, Universal Verification Methodology (UVM), and IP-XACT.
- » Standardize technical implementations developed by Accellera Systems Initiative through the IEEE.

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## Technical Program – Day 1 – Tutorials – December 6, 2022

	Forum 4	Forum 5	Forum 6	Forum 7	Großer Saal
8:30 – 8:45 AM	Opening Session (Ballsaal)				
8:45 – 9:30 AM	Keynote: Challenges in Soc Verification for 5G and Beyond (Ballsaal)				
9:30 – 10:00 AM	Attendee Break (Großer Saal)				Exhibit Hall Open
10:00 – 11:30 AM	T1.1 Functional Safety WG Update	T2.1 An end-to-end approach to design and Verify Battery Management Systems: from Requirements to Virtual Field Testing	T3.1 What is new in IP-XACT IEEE Std. 1685-2022?	T4.1 The Open Source DRAM Simulator DRAMSys4.0	
11:30 – 11:45 AM	Attendee Break (Großer Saal)				
11:45 – 1:15 PM	T1.2 Achieving system dependability: the role of automation and scalability  <small>Silicon to Software</small>	T2.2 Static Signoff Best Practices - Learning and experiences from industry use cases  <small>Powering Intent Driven Sign-off</small>	T3.2 Verification of High- Speed Links through IBIS-AMI Models 	T4.2 A Shift-left Methodology for an early power closure using PowerPro 	
1:15 – 2:15 PM	Lunch (Großer Saal)				
2:15 – 3:45 PM	T1.3 Verification of Virtual Platform Models - What do we Mean with Good Enough?	T2.3 Verification of Inferencing Algorithm Accelerators	T3.3 User Experience Design & EDA - Enable Collaboration on Functional Coverage	T4.3 Efficient Loosely-Timed SystemC TLM-2.0 Modeling: A Hands-On Tutorial	
3:45 – 4:00 PM	Attendee Break (Großer Saal)				
4:00 – 5:30 PM	T1.4 Boost your productivity in FPGA & ASIC design and verification 	T2.4 Fault Injection Analysis for Automotive Safety and Security 	T3.4 Verification 2.0 - Multi Engine, Multi-Run - AI- Driven Verification 		
5:30 – 7:00 PM	Reception (Großer Saal)				

## Technical Program – Day 2 – December 7, 2022

	Forum 4	Forum 5	Forum 6	Forum 7	Großer Saal
8:00 – 8:15 AM	Opening Session (Ballsaal)				
8:15 – 9:15 AM	Keynote: Developing the Chip-to-Cloud Architecture for the Most Desirable Cars (Ballsaal)				
9:15 – 10:30 AM	Panel: 5G Chip Design Challenges and their Impact on Verification (Ballsaal)				
10:30 – 10:45 AM	Attendee Break (Großer Saal)				Exhibit Hall Open
10:45 – 12:15 PM	P1.1 Programmable Analysis of RISC-V Processor Simulations using WAL Automated Creation of Reusable Generators for Analog IC Design with the Intelligent IP Method A Reconfigurable Interface Architecture to Protect System IP	P2.1 A novel and efficient methodology to expedite complex SoC DV closure by leveraging modularly architected scalable environment Using Open-Source EDA in an Industrial Design Flow Soumak: How rich descriptions enable early detection of hookup issues	P3.1 Building Confidence in System level CPU Cache Coherency Verification for Complex SoC’s through a Configurable, Flexible and Portable Test-Bench Unified firmware debug throughout SoC development lifecycle An Accelerated System Level CPU Verification through Simulation-Emulation Co-Existence	P4.1 SAWD: Systemverilog Assertions Waveform-Based Development Tool Register Testing – Exploring Tests, Register Model Libraries, Sequences and Backdoor Access uvm_mem – challenges of using UVM infrastructure in a hierachical verification	
12:15 – 1:15 PM	Lunch (Großer Saal)				
1:15 – 2:45 PM	P1.2 A UVM SystemVerilog Testbench for 5G/LTE Multi-Standard RF Transceiver A novel approach to hardware controlled power aware verification with optimised power consumption techniques at SoC Modelling of UVC Monitor Class as a Finite State Machine for a Packet-Based Interface	P2.2 Automate Interrupt Checking with UVM Macros and Python <b>Poster Presentations</b> Reset Your Reset Domain Crossing (RDC) Verification with Machine Learning A novel approach to expedite MCU verification and enabling efficacious inter-processor communication in a multiprocessor SoC A Novel Approach to Expedite Verification Cycle using an Adaptive and Performance Optimized Simulator Independent Verification Platform Development A novel approach to standardize reusable Modular Plug and Play Skeleton Structure (MPPSS) to expedite verification closure Types of Robustness Test According to DO-254 Guideline for Avionic Systems	P3.2 Development and Verification of RISC-V Based DSP Subsystem IP: Case Study A Cross-domain Heterogeneous ABV-Library for Mixed-signal Virtual Prototypes in SystemC/AMS A Framework for the Execution of Python Tests in SystemC and Specman Testbenches	P4.2 How creativity kills reuse - A modern take on UVM/SV TB architectures Reusable Verification Environment for a RISC-V Vector Accelerator The cost of standard verification methodology implementations	

## Technical Program – Day 2 – December 7, 2022 (Cont)

	Forum 4	Forum 5	Forum 6	Forum 7	Großer Saal
2:45 – 3:15 PM	Attendee Break (Großer Saal)				Exhibit Hall Open
3:15 – 4:45 PM	P1.3 How to achieve verification closure on configurable code by combining static analysis and dynamic testing  Challenges and Solutions for Creating Virtual Platforms of FPGA and SASIC Designs  SIM-V - Fast, Parallel RISC-V Simulation for Rapid Software Verification	P2.3 Efficient Methodology for Mutation-Coverage-Collection of Formal-Property-Checking  How the Right Mindset Increases Quality in RISC-V Verification  Overcoming SystemVerilog Assertions limitations through temporal decoupling and automation	P3.3 Closing the gap between requirement management and circuit design by requirement tracing  A Generic Configurable Error Injection Agent for On-Chip Memories  Agile Approaches to ASIC Verification (A3V) – A Novel Agile Flow in Functional Verification	P4.3 Automated Configuration of System Level C-Based CPU Test-Bench in Modern SoCs: A Novel Framework  Generic Core-Monitor for Hardware/Software Co-Debugging targeting Emulation Platform  Improving Simulation Regression Efficiency using a Machine Learning-based Method in Design Verification	
4:45 – 5:45 PM	Panel: Are processor/SoC discontinuities turning verification on its head? (Ballsaal)				
5:45 – 6:30 PM	Closing Session & Best Paper Award (Ballsaal)				



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**Großer Saal**

**Forum 3**

**Forum 2**

**WC**

**WC**

**U/S-Bahn-Eingang**

**Reception**

**Isar<sup>2</sup> Open Lobby**

**Hoch<sup>2</sup> Bar**

**Lobby**

**Forum 16**

**Forum 15**

**Forum 14**

**Forum 9**

**Forum 10**

**Forum 13**

**Ballsaal**

**Forum 12**

**Forum 11**

**Foyer Ballsaal**

**WC**

**WC**

**Foyer Forum 8**

**Forum 6**

**Forum 4**

**Forum 7**

**Forum 5**

**Foyer Großer Saal**

**Boardroom**

**Forum 8**

**Privat Büro**

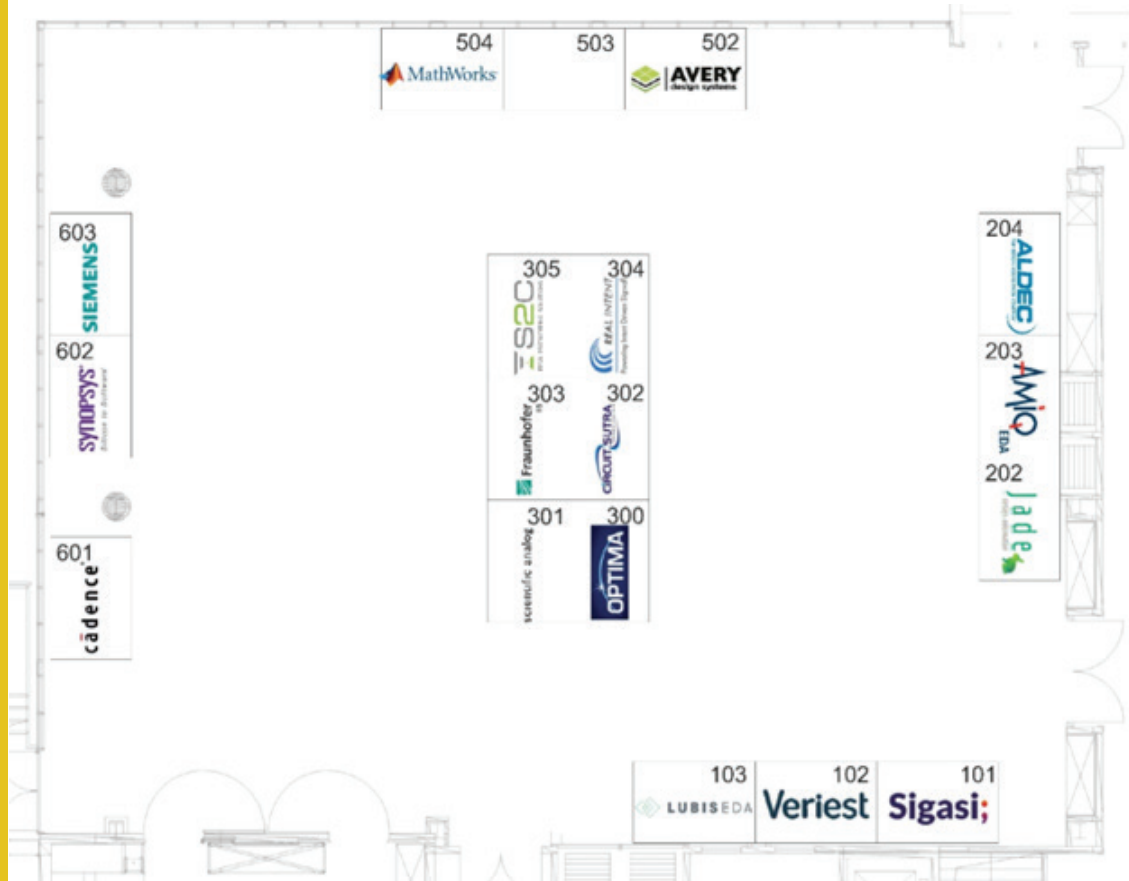
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## DVCon Europe 2022 Exhibit Hall – Großer Saal



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101	Sigasi
102	Veriest Solutions Ltd.
103	LUBIS EDA GmbH
202	Jade Design Automation
203	AMIQ EDA srl
204	Aldec
300	Optima Design Automation Ltd.
301	Scientific Analog, Inc.
302	Circuitsutra Technologies Pvt Ltd
303	Fraunhofer Institute for Integrated Circuits IIS
304	Real Intent Inc.
305	S2C Limited
502	Avery Design Systems
504	Mathworks
601	Cadence Design Systems
602	Synopsys, Inc.
603	Siemens EDA

## Technical Program: Tuesday, December 6

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### Opening Session

8:30:00 AM – 8:45:00 AM

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### Keynote: Challenges in Soc Verification for 5G and Beyond

8:45:00 AM – 9:30:00 AM

#### Ballsaal



#### Axel Jahnke

Bio: Axel Jahnke joined Nokia in 2020 to help with the turnaround of the Nokia SOC. He is now responsible for the L1 ASIC tribe with teams in Tampere, Oulu and Lannion and developing L1 SOC's for base stations for 5G and beyond. Prior to that he worked mainly in R&D positions in companies such as Infineon and Intel, and in design services companies like Wipro and Sondrel; also spending some time at small startups in optical networking and wireless communications.

Abstract: The complexity of chips for basestations for 5G and beyond is driving verification challenges. We will discuss some of the approaches to overcome the challenges and will also talk about the support which is needed from the EDA suppliers.

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### Attendee Break

9:30:00 AM – 10:00:00 AM

#### Großer Saal

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### T1.1: Functional Safety WG Update

10:00:00 AM – 11:30:00 AM

Forum 4

#### Alessandra Nardi

Synopsys

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### T2.1: An end-to-end approach to Design and Verify Battery Management Systems: from Requirements to Virtual Field Testing

10:00:00 AM – 11:30:00 AM

Forum 5

Irina Costachescu<sup>1</sup>; Marius-Lucian Andrei<sup>1</sup>; Manuel Fedou<sup>2</sup>; Conrado Ramirez Garcia<sup>3</sup>

<sup>1</sup> NXP Semiconductors; <sup>2</sup> SpeedGoat; <sup>3</sup> MathWorks

---

### T3.1: What is new in IP-XACT IEEE Std. 1685-2022?

10:00:00 AM – 11:30:00 AM

Forum 6

Dr. Erwin de Kock<sup>1</sup>; Jean-Michel Fernandez<sup>2</sup>; Devender Khari<sup>3</sup>

<sup>1</sup> NXP Semiconductors; <sup>2</sup> ARTERIS IP; <sup>3</sup> Agnisys

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## Technical Program: Tuesday, December 6 (cont.)

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### T4.1: The Open Source DRAM Simulator DRAMSys4.0

10:00:00 AM – 11:30:00 AM

Forum 7  
Dr. Matthias Jung  
Fraunhofer IESE

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### Attendee Break

11:30:00 AM – 11:45:00 AM

Großer Saal

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### T1.2: Achieving system dependability: the role of automation and scalability

11:45:00 AM – 1:15:00 PM

Forum 4  
Teo Cupaiuolo<sup>1</sup>; Paul Baron<sup>2</sup>; Ghani Kanawati<sup>3</sup>  
<sup>1</sup>Synopsys; <sup>2</sup>Melexis; <sup>3</sup>Arm

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### T2.2: Static Signoff Best Practices – Learnings and experiences from industry use cases

11:45:00 AM – 1:15:00 PM

Forum 5  
Vikas Sachdeva



### T3.2: Verification of High-Speed Links through IBIS-AMI Models

11:45:00 AM – 1:15:00 PM

Forum 6  
Ganesh Rathinavel



### T4.2: A shift-left Methodology for an early power closure using PowerPro

11:45:00 AM – 1:15:00 PM

Forum 7  
Mohammed Fahad



### Lunch

1:15:00 PM – 2:15:00 PM

Großer Saal

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### T1.3: Verification of Virtual Platform Models – What do we Mean with Good Enough?

2:15:00 PM – 3:45:00 PM

Forum 4  
PhD Jakob Engblom<sup>1</sup>; Ola Dahl<sup>2</sup>  
<sup>1</sup> Intel Corporation; <sup>2</sup> Ericsson



## Technical Program: Tuesday, December 6 (cont.)

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### T2.3: Verification of Inferencing Algorithm Accelerators

2:15:00 PM – 3:45:00 PM

Forum 5

Russell Klein<sup>1</sup>; Petri Solanti<sup>2</sup>

<sup>1</sup> Mentor Graphics; <sup>2</sup> Siemens EDA

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### T3.3: User Experience Design & EDA – Enable Collaboration on Functional Coverage

2:15:00 PM – 3:45:00 PM

Forum 6

Bodo Hoppe; Jamie Lai

IBM Germany R&D GmbH

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### T4.3: Efficient Loosely-Timed SystemC TLM-2.0 Modeling: A Hands-On Tutorial

2:15:00 PM – 3:45:00 PM

Forum 7

Nils Bosbach<sup>1</sup>; Lukas Jünger<sup>2</sup>

<sup>1</sup> RWTH Aachen University; <sup>2</sup> MachineWare GmbH

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### Attendee Break

3:45:00 PM – 4:00:00 PM

Großer Saal

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### T1.4: Boost your productivity in FPGA & ASIC design and verification

4:00:00 PM – 5:30:00 PM

Forum 4

Bart Brosens

**Sigasi;**

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### T2.4: Fault Injection Analysis for Automotive Safety and Security

4:00:00 PM – 5:30:00 PM

Forum 5

Sesha Sai Kumar C.V., Jamil Mazzawi, Ayman Mouallem



### T3.4: Verification 2.0 – Multi Engine, Multi-Run – AI-Driven Verification

4:00:00 PM – 5:30:00 PM

Forum 6

Matt Graham

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### Reception

5:30:00 PM – 7:00:00 PM

Großer Saal

## Technical Program: Wednesday, December 7

### Opening Session

8:00:00 AM – 8:15:00 AM

Ballsaal

### Keynote: Developing the Chip-to-Cloud Architecture for the Most Desirable Cars

8:15:00 AM – 9:15:00 AM



Ballsaal

**Magnus Oestberg**

**Bio:** Magnus Oestberg joined Mercedes from US automotive supplier Aptiv, where he was Vice President Software Platform & System and responsible for development and launch of the ADAS Satellite Architecture at multiple automotive manufacturers. He started his career in the automotive industry at Mecel, a software and technical consulting company, followed by various management positions at Delphi in Germany and the United States with a focus on vehicle software, infotainment, and telematics.

**Abstract:** Software-based features in cars are impacting the customer experience more than ever. This is as true for Mercedes-Benz as for any other car manufacturer and is particularly important for a luxury brand with sophisticated customers. Magnus Östberg will give insights into Mercedes-Benz' software strategy with focus on their proprietary operating system "MB. OS" as the enabler to create digital luxury.

### Panel: 5G Chip Design Challenges and their Impact on Verification

9:15:00 AM – 10:30:00 AM

Ballsaal

DVCon attendees are invited to learn about the unique challenges of designing chips that support 5G deployment for high-speed cellular networks as well as vertical industries like factories and agriculture. A panel of verification technology and 5G experts will share their knowledge of the current environment, citing practical lessons, real-world case studies and actionable insight into chip design for 5G applications.

The discussion will include examples of how varied end products impact design decisions and architectures. Panelists will suggest whether there is a one size fits all, customized designs or if customization relies on software to achieve application-specific requirements.

5G technology forces compliance with tighter functional objectives and even more demanding integration testing than prior communications technologies. Panelists will be asked to weigh in on the effectiveness of Open RAN and if it creates opportunities for more companies to unveil 5G products.

Such challenges could suggest an overhaul of today's verification and validation environment. Panelists will be asked for their opinions on whether an overhaul of the design and verification environment is needed for 5G requirement or if the same flows that works for CPU, GPUs and other ASIC devices also works for 5G.

Audience participation will be encouraged.



**Moderator**  
**Gabriele Pulini**  
Product Marketing  
and Market  
Development  
Siemens EDA



**Anil Deshpande**  
Associate  
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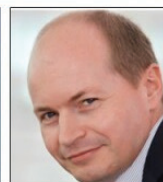
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Design  
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## Technical Program: Wednesday, December 7 (cont.)

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### P1.1

10:45:00 AM – 12:15:00 PM

Forum 4

#### **Programmable Analysis of RISC-V Processor Simulations using WAL**

Lucas Klemmer MSc.<sup>1</sup>; Eyck Jentzsch<sup>2</sup>; Univ.-Prof. Dr. Daniel Große<sup>3</sup>

<sup>1</sup> Johannes Kepler University Linz; <sup>2</sup> MINRES Technologies GmbH; <sup>3</sup> Johannes Kepler Universität Linz

#### **Automated Creation of Reusable Generators for Analog IC Design with the Intelligent IP Method**

Uwe Eichler; Benjamin Prautsch; Dr. Torsten Reich  
Fraunhofer IIS/EAS

#### **A Reconfigurable Interface Architecture to Protect System IP**

Dr. arshad riazuddin; Dr. Shoab Khan  
Center for Advanced Research in Engineering (CARE)

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### P2.1

10:45:00 AM – 12:15:00 PM

Forum 5

#### **A novel and efficient methodology to expedite complex SoC DV closure by leveraging modularly architected scalable environment**

Vinay Swargam<sup>1</sup>; Yatisha Guttapalem<sup>1</sup>; Ayush Agrawal; Sriram Kazhiyur Sounderrajan; Somasunder Katteppura Sreenath

<sup>1</sup> Samsung Semiconductor India R & D Centre(SSIR)

#### **Using Open-Source EDA in an Industrial Design Flow**

Daniela Sanchez Lopera MSc.<sup>1</sup>; Prajwal Kashyap<sup>1</sup>; Nicolas Gerlin<sup>1</sup>; Sven Wenzek<sup>2</sup>; Prof. Dr. Wolfgang Ecker<sup>1</sup>

<sup>1</sup> Infineon Technologies AG; <sup>2</sup> EPOS Embedded Core & Power Systems

#### **Soumak: How rich descriptions enable early detection of hookup issues**

Peter Birch; Dr. Thomas Brown PhD  
Graphcore Ltd

## Technical Program: Wednesday, December 7 (cont.)

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### P3.1

10:45:00 AM – 12:15:00 PM

Forum 6

#### **Building Confidence in System level CPU Cache Coherency Verification for Complex SoC's through a Configurable, Flexible and Portable Test-Bench**

Ruchi Misra<sup>1</sup>; Shrinidhi Rao<sup>1</sup>; Alok Kumar<sup>1</sup>; Garima Srivastava<sup>1</sup>; Youngsik Kim<sup>2</sup>; Seonil Brian Choi<sup>2</sup>

<sup>1</sup> Samsung Semiconductor India R & D Centre(SSIR); <sup>2</sup> Samsung Electronics, Korea

#### **Unified firmware debug throughout SoC development lifecycle**

Dimitri Ciaglia<sup>1</sup>; Dr. Thomas Winkler<sup>1</sup>; Dr. Jurica Kundrata PhD<sup>2</sup>

<sup>1</sup> ams-OSRAM International GmbH; <sup>2</sup> University of Zagreb

#### **An Accelerated System Level CPU Verification through Simulation-Emulation Co-Existence**

Ruchi Misra<sup>1</sup>; Samridh Deva<sup>1</sup>; Sai Krishna Pallekonda; Alok Kumar<sup>1</sup>; Garima Srivastava<sup>1</sup>; Youngsik Kim<sup>2</sup>; Seonil Brian Choi<sup>2</sup>

<sup>1</sup> Samsung Semiconductor India R & D Centre(SSIR); <sup>2</sup> Samsung Electronics, Korea

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### P4.1

10:45:00 AM – 12:15:00 PM

Forum 7

#### **SAWD: Systemverilog Assertions Waveform-Based Development Tool**

Ahmed Alsawi  
Qualcomm

#### **Register Testing – Exploring Tests, Register Model Libraries, Sequences and Backdoor Access**

Rich Edelman  
Siemens EDA

#### **uvm\_mem – challenges of using UVM infrastructure in a hierarchical verification**

Joachim Geishauser<sup>1</sup>; Aditya Chopra; Stephan Ruettiger; Sanjay Kakasaniya; Luca Rossi; Lina Zhang

<sup>1</sup> NXP Semiconductors Germany GmbH

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### Lunch

12:15:00 PM – 1:15:00 PM

Großer Saal



## Technical Program: Wednesday, December 7 (cont.)

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### P1.2

1:15:00 PM – 2:45:00 PM

Forum 4

#### **A UVM SystemVerilog Testbench for 5G/LTE Multi-Standard RF Transceiver**

ByeongKyu Kim; Prof. Jaeha Kim

#### **A novel approach to hardware controlled power aware verification with optimised power consumption techniques at SoC**

Eldin Ben Jacob; Harshal Kothari; Sriram Kazhiyur Soundarrajan; Somasunder Katteppura Sreenath

#### **Modelling of UVC Monitor Class as a Finite State Machine for a Packet-Based Interface**

Djordje Velickovic; Milos Mitic

Veriest Solutions

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### P2.2 + Poster Presentations

1:15:00 PM – 2:45:00 PM

Forum 5

#### **Automate Interrupt Checking with UVM Macros and Python**

Aleksandra Dimanic MSc.; Nemanja Stevanovic<sup>1</sup>; Yoav Furman<sup>2</sup>; Itay Henigsberg<sup>2</sup>

<sup>1</sup> Vtool LTD; <sup>2</sup> Chain Reaction Ltd

#### **Reset Your Reset Domain Crossing (RDC) Verification with Machine Learning**

Mark Handover

Siemens EDA

#### **A novel approach to expedite MCU verification and enabling efficacious inter-processor communication in a multiprocessor SoC**

Harshal Kothari; Manishadevi Satyanarayana Cheernam; Vignesh Adiththan; Sriram Kazhiyur Soundarrajan; Somasunder Katteppura Sreenath

#### **A Novel Approach to Expedite Verification Cycle using an Adaptive and Performance Optimized Simulator Independent Verification Platform Development**

Harshal Kothari; Vinay Swargam; Sriram Kazhiyur Soundarrajan; Somasunder Katteppura Sreenath

#### **A novel approach to standardize reusable Modular Plug and Play Skeleton Structure (MPPSS) to expedite verification closure**

Himanshu Dixit; Chandrachud Murali; Sriram Kazhiyur Soundarrajan; Somasunder Katteppura Sreenath

Samsung Semiconductor India R & D Centre(SSIR)

#### **Types of Robustness Test According to DO-254 Guideline for Avionic Systems**

Gözde Asena KILINÇ; Yavuz AKSU; Fatih BAYSAL

ASELSAN A.Ş.

## Technical Program: Wednesday, December 7 (cont.)

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### P3.2

1:15:00 PM – 2:45:00 PM

Forum 6

#### Development and Verification of RISC-V Based DSP Subsystem IP: Case Study

Larry Lapides<sup>1</sup>; Olivier Montfort<sup>2</sup>; Pascal Gouedo<sup>2</sup>; Damien Le Bars<sup>2</sup>; Lee Moore<sup>1</sup>; Aimee Sutton<sup>1</sup>

<sup>1</sup> Imperas Software Ltd.; <sup>2</sup> Dolphin Design

#### A Cross-domain Heterogeneous ABV-Library for Mixed-signal Virtual Prototypes in SystemC/AMS

Muhammad Hassan<sup>1</sup>; Dr. Thilo Vörtler<sup>2</sup>; Karsten Einwich<sup>2</sup>; Prof. Dr. Rolf Drechsler<sup>3</sup>; Prof. Dr. Daniel Große<sup>4</sup>

<sup>1</sup> DFKI GmbH; <sup>2</sup> COSEDA Technologies GmbH; <sup>3</sup> University of Bremen & DFKI GmbH; <sup>4</sup> Johannes Kepler University, Linz, Austria & DFKI GmbH Bremen

#### A Framework for the Execution of Python Tests in SystemC and Specman Testbenches

Christoph Tietz<sup>1</sup>; Sebastian Stieber<sup>2</sup>; Najdet Charaf<sup>3</sup>; Prof. Dr.-Ing. Diana Göhringer

<sup>1</sup> Bosch Sensortec; <sup>2</sup> StZ System-Level-Modellierung und Integration von MEMS Sensorsystemen; <sup>3</sup> Technische Universität Dresden; Technische Universität Dresden

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### P4.2

1:15:00 PM – 2:45:00 PM

Forum 7

#### How creativity kills reuse – A modern take on UVM/SV TB architectures

Andrei Vintila; Sergiu Duda  
Amiq Consulting

#### Reusable Verification Environment for a RISC-V Vector Accelerator

Josue Quiroga<sup>1</sup>; Roberto Ignacio Genovese MSc<sup>1</sup>; Iván Díaz Ortega<sup>1</sup>; Henrique Yano<sup>1</sup>; Asif Ali<sup>1</sup>; Nehir Sonmez PhD<sup>1</sup>; Oscar Palomar PhD<sup>1</sup>; Victor Jiménez Arador<sup>2</sup>; Mario Rodriguez Perez<sup>3</sup>; Marc Dominguez de la Rocha<sup>3</sup>

<sup>1</sup> Barcelona Supercomputing Centre (BSC), Spain; <sup>2</sup> MaxLinear; <sup>3</sup> Cudasip

#### The cost of standard verification methodology implementations

Svetlomidir Hristozkov; Adam Hizey; Abigail Williams  
Graphcore Ltd

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### Attendee Break / Poster Session

2:45:00 PM – 3:15:00 PM

Großer Saal

## Technical Program: Wednesday, December 7 (cont.)

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### P1.3

3:15:00 PM – 4:45:00 PM

Forum 4

#### **How to achieve verification closure on configurable code by combining static analysis and dynamic testing**

Dr. Antonello Celano<sup>1</sup>; Alexandre Langenieux<sup>2</sup>

<sup>1</sup> ST Microelectronics; <sup>2</sup> The MathWorks GmbH

#### **Challenges and Solutions for Creating Virtual Platforms of FPGA and SASIC Designs**

Kalen Brunham; Jakob Engblom

Intel Corporation

#### **SIM-V – Fast, Parallel RISC-V Simulation for Rapid Software Verification**

Lukas Jünger<sup>1</sup>; Dr. Jan Weinstock<sup>1</sup>; Prof. Rainer Leupers

<sup>1</sup> MachineWare GmbH

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### P2.3

3:15:00 PM – 4:45:00 PM

Forum 5

#### **Efficient Methodology for Mutation-Coverage-Collection of Formal-Property-Checking**

Dr. Holger Busch

Infineon Technologies

#### **How the Right Mindset Increases Quality in RISC-V Verification**

Philippe LUC<sup>1</sup>; Salahhedin Hetalani<sup>2</sup>; Nicolae Tusinschi<sup>2</sup>

<sup>1</sup> CODASIP; <sup>2</sup> Siemens EDA

#### **Overcoming SystemVerilog Assertions limitations through temporal decoupling and automation**

Master Degree Mattia De Pascalis MSc<sup>1</sup>; Xia Wu<sup>2</sup>; Matteo Vottero<sup>3</sup>; Jacob Sander Andersen<sup>4</sup>

<sup>1</sup> SyoSil; <sup>2</sup> Verification Lead, SyoSil ApS, Høje Taastrup, Denmark; <sup>3</sup> Verification Engineer, SyoSil ApS, Høje Taastrup, Denmark; <sup>4</sup> CTO, SyoSil ApS, Høje Taastrup, Denmark

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### P3.3

3:15:00 PM – 4:45:00 PM

Forum 6

#### **Closing the gap between requirement management and circuit design by requirement tracing**

Hayri Verner Hasou<sup>1</sup>; Guillermo Conde<sup>1</sup>; Adrian Rolufs<sup>2</sup>; Thomas Arndt<sup>3</sup>; Dominic Scharfe<sup>3</sup>

<sup>1</sup> Infineon Technologies; <sup>2</sup> Jamasoftware; <sup>3</sup> COSEDA Technologies GmbH

#### **A Generic Configurable Error Injection Agent for On-Chip Memories**

Anil Deshpande<sup>1</sup>; Niharika Sachdeva<sup>1</sup>; Arjun Suresh Kumar<sup>1</sup>; Damandeep Saini<sup>1</sup>; Ravi Teja Gopagiri<sup>1</sup>; Somasunder KS<sup>1</sup>; Jaechul Park<sup>2</sup>

<sup>1</sup> Samsung Semiconductor India R & D Centre(SSIR); <sup>2</sup> Samsung Electronics, Korea

#### **Agile Approaches to ASIC Verification (A3V) – A Novel Agile Flow in Functional Verification**

Adithya Rangan; Vidyasagar Kantamneni; Vishal Dalal

Infineon Technologies Bengaluru (India)

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## Technical Program: Wednesday, December 7 (cont.)

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**P4.3**

**3:15:00 PM – 4:45:00 PM**

Forum 7

### **Automated Configuration of System Level C-Based CPU Test-Bench in Modern SoCs : A Novel Framework**

Ruchi Misra<sup>1</sup>; Chetan Kulkarni<sup>1</sup>; Alok Kumar<sup>1</sup>; Garima Srivastava<sup>1</sup>; Youngsik Kim<sup>2</sup>; Seonil Brian Choi<sup>2</sup>

<sup>1</sup> Samsung Semiconductor India R & D Centre(SSIR); <sup>2</sup> Samsung Electronics, Korea

### **Generic Core-Monitor for Hardware/Software Co-Debugging targeting Emulation Platform**

Shreya Morgansgate<sup>1</sup>; Dr. Johannes Grinschgl<sup>2</sup>; Dr. Djones Lettnin<sup>2</sup>

<sup>1</sup> Infineon Technologies AG Germany ; <sup>2</sup> Infineon Technologies AG Germany

### **Improving Simulation Regression Efficiency using a Machine Learning-based Method in Design Verification**

Deepak Narayan Gadde<sup>1</sup>; Sebastian Simon<sup>1</sup>; Djones Lettnin<sup>2</sup>; Thomas Ziller<sup>3</sup>

<sup>1</sup> Infineon Technologies Dresden GmbH & Co. KG; <sup>2</sup> Infineon Technologies AG ; <sup>3</sup>

Cadence Design Systems GmbH

## Technical Program: Wednesday, December 7 (cont.)

### Panel: Are processor/SoC discontinuities turning verification on its head?

4:45:00 PM – 5:45:00 PM

Ballsaal

A symbiotic relationship exists between modern System-on-Chip (SoC) requirements and processor technology evolution. As SoCs are applied to a broader range of applications with specialized needs, for example safety and security in the case of automotive and medical electronics, processor suppliers must adapt their devices accordingly while ensuring that performance and power objectives continue to be met.

To meet these needs, processor clusters leverage specialized instructions and accelerators across coherent fabrics driven by performance optimized software. This has recently been augmented by the advent of open instruction set architectures and the inclusion of custom instructions. The impact of this evolution is most felt during the verification process. Ensuring instruction set compatibility and efficient load-store operation in processor that must meet ever more stringent SoC requirements has verification teams scrambling. Are we at a verification inflexion point where the whole process requires revamping?

Mike Bartley, a well-known verification technologist and commentator, will moderate this panel made up of verification experts on the frontline of SoC challenges. They will explore evolving SoC requirements, the impact of new processor developments and their own experience at meeting corresponding verification needs. Expert panelists from a leading processor provider and SoC integrator will compare their findings with two noted EDA SoC/processor verification company leaders. Attendees will learn what is coming in terms of SoC developments and strategies for dealing with these. Audience participation will be encouraged.



**Moderator:**  
**Mike Bartley**  
Senior Vice  
President  
Tessolve



**Duncan  
Graham**  
Applications  
Engineering  
Specialist  
Imperas



**Bodo Hoppe**  
Distinguished  
Engineer  
Verification  
IBM



**David Kelf**  
CEO  
Breker  
Verification  
Systems



**Philippe Luc**  
Director of  
Verification  
Codasip

### Closing Session & Best Paper Award

5:45:00 PM – 6:30:00 PM

Ballsaal



## SystemC Evolution Day 2022



Workshop on the Evolution of SystemC Standards, held on 8 December 2022

The seventh SystemC Evolution Day is a full-day, technical workshop on the evolution of SystemC standards to advance the SystemC ecosystem. In several in-depth sessions, selected current and future standardization topics around SystemC will be discussed in order to accelerate their progress for inclusion in Accellera/IEEE standards.

SystemC Evolution Day is intended as a lean, user-centric, hands-on forum bringing together experts from the SystemC user community and the Accellera Working Groups to advance SystemC standards.

### Event information

**Date:** 8 December 2022 (day after DVCon Europe 2022)

**Time:** 09:00 – 17:00 CEST

**Location:** Holiday Inn Munich City Centre, Hochstrasse 3, 81669 Munich, Germany

### Registration

Registration fee is €50. Register [here](#).

### Organization Team:

- » **Ola Dahl**, Ericsson (Chair)
- » **Martin Barnasconi**, NXP
- » **Jerome Cornet**, STMicroelectronics
- » **Christian Sauer**, Cadence
- » **Mark Burton**, Qualcomm
- » **Peter de Jager**, Intel

### Program

The main theme this year is Evolution and Ecosystem: Besides the developments of the SystemC standard and its implementations, we like to broaden our view to see and learn how SystemC is used, or could be used, in other system modeling and simulation environments around us.

Exploring this bigger ecosystem, and understanding the role of SystemC in such ecosystem, is vital to identify new requirements and features to be developed as part of the SystemC ecosystem or beyond, by means of adapters, interfaces or other intercommunication concepts.

The (tentative) program of the SystemC Evolution Day will cover the following topics:

- » Introduction – Evolution and Ecosystem
- » SystemC standardization in IEEE
- » Accellera update
- » Virtualization and Emulation with QEMU and SystemC
- » Distributed simulation and SystemC
- » Panel & Discussion – System modeling and simulation – now and in the future



• **Save the Date!**

**DVCon Europe 2023**

HOLIDAY INN MUNICH – CITY CENTRE | MUNICH, GERMANY

• **November 14-15, 2023**